

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

#### PCN#20210628001.1 New nfBGA Tray for Select Devices Final Change Notification

Date:July 12, 2021To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team SC Business Services

#### 20210628001.1 Attachment: 1

#### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

#### DEVICE

#### **CUSTOMER PART NUMBER**

TM4C1290NCZADT3 TM4C1299NCZADI3 TM4C129LNCZADT3

null null null

Technical details of this Product Change follow on the next page(s).

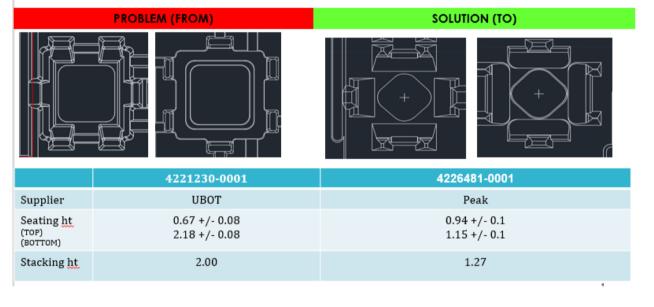
PCN Number:			20210628001.1				Ρ	CN I	Date: July 12, 2021			
			Tray for Select Devices									
Customer Contact:			PCN Manager			Dept:	(	Quality Services				
Proposed 1 <sup>st</sup> Ship Da												
Change Type:												
	Assembly Site			Design				Wafer			r Bump Site	
Assembly Process			📃 Data She			eet	et 📃 🗌 Wafer Bump			r Bump Material		
Assembly Material			s 📃 Part nur			nber change	Wafer Bump Proces			r Bump Process		
Mechanical Specifi			cation 🛛 🗌 Test Site			2			Wafer Fab Site			
Packing/Shipping/Labeling				ing	Test Process					Wafer Fab Materials		
										Wafe	r Fab Process	
PCN Details												

Description of Change:

Texas Instruments is pleased to announce the qualification of a new nfBGA tray for the devices listed below. A comparison summary of the tray differences are as follows:

## Group 1 Tray Comparison Tables:

# Description of Change/Change Proposal: 10x10 BGA (thin)



ITEM DESCRIPTION	CURRENT TRAY: 4221230-0001			PROPOSED: 4226481-0001			COMMENT
TTEM DESCRIPTION	DIM	Upper Limits	Lower Limits	DIM	Upper Limits	Lower Limits	COMMENT
Overall Length	322.6	322.85	322.35	322.6	322.85	322.35	NO CHANGE
Layout Length	315.0	315.25	314.75	315.0	315.25	314.75	NO CHANGE
Layout Width	135.9	136.15	135.65	135.9	136.15	135.65	NO CHANGE
Layout Length on Top Stack frame	311.15	311.40	311.02	311.15	311.40	311.02	NO CHANGE
Layout Width on Top Stack frame	132.08	132.33	131.95	132.08	132.33	131.95	NO CHANGE
Layout Length on Bottom Stack frame	311.66	311.91	311.53	311.66	311.91	311.53	NO CHANGE
Layout Width on Bottom Stack frame	132.59	132.84	132.46	132.59	132.84	132.46	NO CHANGE
End Tab Length	92.1	92.35	91.85	92.1	92.35	91.85	NO CHANGE
Overall Height	7.62	7.75	7.49	7.62	7.75	7.49	NO CHANGE
Stack Height	2.00	2.13	1.87	1.27	1.40	1.14	CHANGE
Tray Matrix No.	08x23			08×23			NO CHANGE
Pitch M	19.65	19.78	19.52	19.65	19.78	19.52	NO CHANGE
Pitch M3	13.80	13.93	13.67	13.80	13.93	13.67	NO CHANGE
Pitch M1	10.10	10.23	9.97	10.10	10.23	9.97	NO CHANGE
Pitch M2	13.40	13.53	13.27	13.40	13.53	13.27	NO CHANGE
Cavity Size	10.30	10.38	10.22	10.3	10.38	10.22	NO CHANGE
Package seating height (Top)	0.67	0.75	0.59	0.94	1.04	0.84	CHANGE
Package seating height (Bottom)	2.18	2.26	2.10	1.15	1.25	1.05	CHANGE

## Group 2 Tray Comparison Tables:

# Description of Change/Change Proposal: 6x6 BGA



ITEM DESCRIPTION	CURREN	NT TRAY : 42	18374-0001	PROF	OSED: 4226	235-0001	COMMENT
TILM DESCRIPTION	DIM	Upper Limits	Lower Limits	DIM	Upper Limits	Lower Limits	COMPLEXI
Overall Length	322.6	322.85	322.35	322.6	322.85	322.35	NO CHANGE
Layout Length	315.0	315.25	314.75	315.0	315.25	314.75	NO CHANGE
Layout Width	135.9	136.15	135.65	135.9	136.15	135.65	NO CHANGE
Layout Length on Top Stack frame	311.15	311.40	311.02	311.15	311.40	311.02	NO CHANGE
Layout Width on Top Stack frame	132.08	132.33	131.95	132.08	132.33	131.95	NO CHANGE
Layout Length on Bottom Stack frame	311.66	311.91	311.53	311.66	311.91	311.53	NO CHANGE
Layout Width on Bottom Stack frame	132.59	132.84	132.46	132.59	132.84	132.46	NO CHANGE
End Tab Length	92.1	92.35	91.85	92.1	92.35	91.85	NO CHANGE
Overall Height	7.62	7.75	7.49	7.62	7.75	7.49	NO CHANGE
Stack Height	2.00	2.13	1.87	1.27	1.40	1.14	CHANGE
Tray Matrix No.		10x25			10x25		NO CHANGE
Pitch M	9.00	9.13	8.87	9.00	9.13	8.87	NO CHANGE
Pitch M3	13.10	13.23	12.97	13.10	13.23	12.97	NO CHANGE
Pitch M1	8.70	8.83	8.57	8.70	8.83	8.57	NO CHANGE
Pitch M2	12.40	12.53	12.27	12.40	12.53	12.27	NO CHANGE
Distance of tray singulation from corner of tray	34.3	34.55	34.05	34.3	34.55	34.05	NO CHANGE
Tray singulation width	25.40	25.53	25.27	25.4	25.53	25.27	NO CHANGE
Tray Lifting surface height	2.54	2.67	2.41	2.54	2.67	2.41	NO CHANGE
Cavity Size (X)	6.20	6.33	6.12	6.25	6.33	6.17	CHANGE
Cavity Size (Y)	6.20	6.33	6.12	6.25	6.33	6.17	CHANGE
Pedestal Design	F	LOORSUP	PORT	F	LOORSUP	PORT	NO CHANGE
Package seating height (Top)	2.00	2.08	1.92	1.35	1.45	1.25	CHANGE
Package seating height (Bottom)	2.00	2.08	1.92	1.32	1.42	1.22	CHANGE

#### **Reason for Change:**

New tray offers improvement on tray warpage, chipping, stuck up caused by current tray

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None

#### **Changes to product identification resulting from this PCN:**

New tray

#### Group 1 Product Affected:

MSP432E411YTZAD	TM4C1297NCZADT3	TM4C129DNCZADI3	TM4C129XNCZADI3
TM4C1290NCZADI3	TM4C1299KCZADI3	TM4C129DNCZADT3	TM4C129XNCZADT3
TM4C1290NCZADT3	TM4C1299KCZADT3	TM4C129ENCZADT3	TM4E129BNCZADI3
TM4C1292NCZADT3	TM4C1299NCZADI3	TM4C129LNCZADT3	TM4E129BNCZADT3
TM4C1294NCZADT3	TM4C1299NCZADT3	TM4C129XKCZADI3	TM4E129XNCZADI3
TM4C1297NCZADI3	TM4C129CNCZADT3	TM4C129XKCZADT3	
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### **Group 2 Product Affected:**

MSP430FR59941IZVW MSP430FR5994IZVW TLV320AIC34IZAS

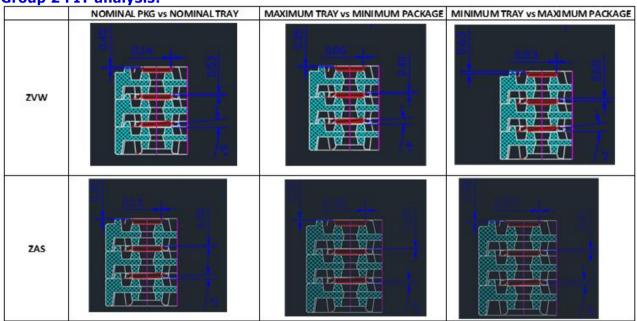
## Group 1 FIT analysis:

	NOMINAL PKG vs NOMINAL TRAY	MAXIMUM TRAY vs MINIMUM PACKAGE	MINIMUM TRAY vs MAXIMUM PACKAGE
ZAD	0,465 0,150 0,150 3°		0.622 0.240 0.240 5°

REMARKS:

Rotation is less than 10 degrees

Lateral distance clearance is less than 0.5 mm



#### Group 2 FIT analysis:

#### REMARKS:

- Rotation is less than 10 degrees
- Lateral distance clearance is less than 0.5 mm

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

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